

PATENT ASSIGNMENT

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 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chia-Jung Li</td> <td>03/19/2013</td> </tr> <tr> <td>Chia-Jui Liang</td> <td>03/19/2013</td> </tr> <tr> <td>Po-Chao Tsao</td> <td>03/19/2013</td> </tr> <tr> <td>Ching-Ling Lin</td> <td>03/19/2013</td> </tr> <tr> <td>En-Chiuan Liou</td> <td>03/19/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chia-Jung Li	03/19/2013	Chia-Jui Liang	03/19/2013	Po-Chao Tsao	03/19/2013	Ching-Ling Lin	03/19/2013	En-Chiuan Liou	03/19/2013
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Ching-Ling Lin	03/19/2013												
En-Chiuan Liou	03/19/2013												
RECEIVING PARTY DATA													
Name:	UNITED MICROELECTRONICS CORP.												
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park												
City:	Hsin-Chu City												
State/Country:	TAIWAN												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13851113</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13851113								
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Application Number:	13851113												
CORRESPONDENCE DATA													
Fax Number:	7039974517												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	3027291562												
Email:	Patent.admin.uspto.cr@naipo.com												
Correspondent Name:	WINSTON HSU												
Address Line 1:	P.O.BOX 506												
Address Line 4:	Merrifield, VIRGINIA 22116												
ATTORNEY DOCKET NUMBER:	NAUP1618USA												
NAME OF SUBMITTER:	SIBYL YU												
Total Attachments: 10 source=1608283#page1.tif													

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR DEVICE

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.
IN WINTNESS WHEREOF, I have hereunto set hand and seal this MAR 19 2013 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No NAUP1618USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chia-Jung Li

Date: MAR 19 2013

Signature: Chia-Jung Li

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Docket No NAUP1618USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chia-Jui Liang**

Date: **MAR 19 2013**

Signature: Chia-Jui Liang

NPO#NAU-P1618-USA:0
CUST#UMCD-2012-0377

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F#NPO-P0002E-US1201
DSC0-102U000770

PATENT
REEL: 030092 FRAME: 0490

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

**METHOD FOR FABRICATING PATTERNED STRUCTURE OF SEMICONDUCTOR
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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Po-Chao Tsao**

Date: **MAR 19 2013**

Signature: Po-Chao Tsao

NPO#NAU-P1618-USA:0
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F#NPO-P0002E-US1201
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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ching-Ling Lin**

Date: **MAR 19 2013**

Signature: Ching-Ling Lin.

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Inventor: **En-Chiuan Liou**

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